



Product / Process Change Notice

No.: Z200-PCN-DM201912-03-A

Date: December 18, 2019

Change Title : W25R128JV 3.3V RPMC Flash to replace W25R128FV 3.3V RPMC Flash Memories

Change Classification: Major Minor with customer notification Minor without customer notification

Change item : Design Raw Material Wafer FAB Assembly Testing Packing Others

Affected Product(s) :

W25R128FVEIQ , W25R128FVPIG , W25R128FVPIQ , W25R128FVSIQ

Description of Change(s)

W25R128JV 3.3V RPMC Flash Memories is using Winbond 58nm Flash technology, It is function-compatible with W25R128FV 3.3V RPMC devices and offering improved performance, features and availability.

1. Individual Block/Sector array protection.
2. Special OTP protection. (Please refer the W25R128JV RPMC datasheet)

Reason for Change(s) :

1. W25R128FV RPMC EOL. (Please refer to attachment IV for details)
2. New generation features improvement and Command backward compatible. (Please refer to attachment I comparison table)

Impact of Change(s) : (positive & negative)

Form : No Change

Fit : No Change

Function : No Concern (Please refer to attachment I)

Reliability : No Concern (Please refer to attachment II)

Hazardous Substances: No Concern (Please refer to attachment III)

Qualification Plan/ Results :

Based on Winbond W25R Reliability report, the new product meets our criteria and no quality concern (refer to Attachment II in details)

Implementation Plan :

Please refer to attachment IV for details.

Date Code: ____ onward Lot No: ____ onward Proposed first ship date: Please refer to attachment IV.

Originator: (QA)

Hyhuang

Approval: (QA Dept. Manager)

YH Cheng

Approval: (QRA Director)

Garvin Chen

Contact for Questions & Concerns

Name: Betty Huang TEL: 886-3-5678168 (ext.76549) FAX: 886-3-5796124
 Address : No. 8,Keya 1st Rd., Daya Dist., Central Taiwan Science Park, Taichung City 42881,Taiwan
 E-mail: Hyhuang8@winbond.com



Customer Comments:

Note: Please sign this notice, and return to Winbond contact within 30 days. If no response is received within 30 days, this Change Request will be assumed to meet your approval.

Major change: Approval Disapproval Conditional Approval : _____.

Minor change with customer notification: Recognition

Minor change without customer notification: Approval Disapproval

Conditional Approval : _____

Comment:

Date: _____

Dept. name: _____

Person in charge: _____



Winbond Electronics Corporation

6F., No.38, Gaotie 1st Rd., Jhubei City,
Hsinchu County 30273, Taiwan R.O.C.

Product Obsolescence Notice

W25R128FV 3.3V RPMC Memories

Notification Date: December 16, 2019

Dear Valued Customer,

This letter is to notify you of Winbond's intention to terminate production of the W25R128FV 3.3V RPMC memory, and replace it with the W25R128JV 3.3V RPMC Flash. Replacement part numbers are listed below:

Winbond Current PN (58nm F-Series)	Winbond Primary Replacement PN (58nm J-Series)
W25R128FVSIQ	W25R128JVSIQ
W25R128FVPIQ	W25R128JVPIQ
W25R128FVPIG	
W25R128FVEIQ	W25R128JVEIQ

The W25R128JV 3.3V RPMC device features:

Features

- a) Command backward compatible with W25R128JV 3.3V RPMC Flash
- b) Clock operation up to 104MHz, SPI with Single / Dual / Quad / QPI
- c) Individual Block/Sector array protection

Please refer to the table below for your particular product last time order date and Winbond last shipment date and use this table to determine your last time buys and subsequent request dates. Winbond Electronics reserves the right to limit last time buy quantities based on capacity and material availability. Please notify Winbond as soon as possible if there are any concerns with these this schedule.

Part Number	Notification Date	Last Order Date	Last Ship Date	Part Number	Reliability Report	Mass Production
W25R128FV	Dec./16/ 2019	Jun./16/ 2020	Dec./16/ 2020	W25R128JV	Sep./20 2019	Oct./30/ 2019

Jooweon (JW) Park
Technology Executive of Flash Marketing